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die oriented having said at least one electrical connection area substantially aligned with
said at least one semiconductor substrate opening; and

at least one adhesive tape interposed between and attaching said semiconductor die active surface and said semiconductor substrate first surface, wherein a width of said at least one adhesive tape extends proximate an edge of said at least one semiconductor die to proximate an edge of said at least one semiconductor substrate opening; [and said at least one semiconductor die is oriented such that said at least one electrical connection area is aligned with said at least one semiconductor substrate opening].

REMARKS

Claims 1 through 15 are currently pending in the application.

Applicant submits that the present amendment complies with the provisions of 35 U.S.C. § 132 as no new matter has been added.

The Applicant requests entry of the foregoing amendment prior to examination of the application on the merits.

Respectfully submitted,

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Date: November 6, 2000

JRD/bv